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Class H equivalent die up-screening

MIL-PRF-38534 Class H Equivalent Up-Screening Rev L		
Screening Requirements		
Test	Quantity (Accept Number of Failures)	Specification and Test Method
Subgroup 1: Electrical Test	100%	
Subgroup 2: Visual Inspection	100%	MIL-STD-750: 2069, 2070, 2072, 2073
Subgroup 3A: Internal/Die Visual Inspection	10 (0)	MIL-STD-750: 2069, 2070, 2072, 2073
Subgroup 3B: Sample Assembly	10 (0)	
Subgroup 4: Electrical Test as per Datasheet: DC Test @ 25°C / DC Test @ 125°C / DC Test @-55°C/ (DC1-DC3)	10 (0)	
Subgroup 5 Wire Pull	10 Wires (0) or 20 Wires (1)	MIL-STD-883: 2011 Cond. D 1 Hour 300C Pre-Test Bake (Bimetallic Bonds Only)

Note: Devices supplied will be to the test flow illustrated above. Any changes to the flow must be agreed upon in writing by the customer and Central Semiconductor Corp.